

IN THE CLAIMS:

The status of each claim that has been introduced in the above-referenced application is identified in the ensuing listing of the claims. This listing of the claims replaces all previously submitted claims listings.

1. (Currently amended) A method for establishing an electrical contact with at least one semiconductor device, comprising:  
establishing an electrical contact between a first member of an electrical connector and a contact that is in electrical communication with the at least one semiconductor device; and drawing ~~said~~ the first member toward ~~said~~ the contact.

2. (Currently amended) The method of claim 1, wherein ~~said~~ the drawing is effected in a direction substantially normal to a plane of ~~said~~ the contact.

3. (Currently amended) The method of claim 1, wherein ~~said~~ the drawing is effected in a direction substantially normal to a plane of a substrate upon which ~~said~~ the contact is carried.

β3 4. (Currently amended) The method of claim 1, wherein ~~said~~ the drawing is effected by positioning a second member of ~~said~~ the electrical connector opposite ~~said~~ the first member.

5. (Currently amended) The method of claim 4, wherein ~~said~~ the drawing is effected by magnetically attracting at least one of ~~said~~ the first member and ~~said~~ the second member toward at least the other of ~~said~~ the first member and ~~said~~ the second member.

6. (Currently amended) The method of claim 4, wherein ~~said~~ the drawing comprises securing ~~said~~ the first and second members to a substrate upon which ~~said~~ the contact is carried.

7. (Currently amended) The method of claim 1, wherein ~~said~~ the drawing comprises magnetically attracting ~~said~~ the first member against ~~said~~ the contact.

8. (Currently amended) A method for stress testing a plurality of semiconductor devices carried upon a common substrate and in communication with common ground and power contacts, comprising:

establishing electrical contact between a first member of an electrical connector and at least one

contact of the ground contact and the power contact; and

drawing ~~said~~ the first member toward ~~said~~ the at least one contact.

9. (Currently amended) The method of claim 8, wherein ~~said~~ the drawing is effected in a direction substantially normal to a plane of the substrate.

B3  
10. (Withdrawn)

11. (Currently amended) The method of claim 8, wherein ~~said~~ the drawing comprises positioning a second member of ~~said~~ the electrical connector opposite the substrate from ~~said~~ the first member.

12. (Currently amended) The method of claim 11, wherein at least one of ~~said~~ the first member and ~~said~~ the second member is drawn toward at least the other of ~~said~~ the first member and ~~said~~ the second member.

13. (Currently amended) The method of claim 12, wherein ~~said~~ the drawing comprises magnetically attracting at least one of ~~said~~ the first member and ~~said~~ the second member toward at least the other of ~~said~~ the first member and ~~said~~ the second member.

14. (Currently amended) The method of claim 8, wherein ~~said~~ the drawing comprises magnetically attracting ~~said~~ the first member against ~~said~~ the at least one contact.

15. (Currently amended) The method of claim 8, wherein ~~said~~ the drawing comprises securing at least ~~said~~ the first member in position relative to the substrate.

16. (Currently amended) The method of claim 8, further comprising:  
electrically connecting another first member of another electrical connector to another of the  
ground contact and the power contact; and  
drawing ~~said~~ the another first member toward ~~said~~ the another contact.

17. (Currently amended) The method of claim 16, further comprising:  
applying a substantially constant amount of current to each semiconductor device of the plurality  
of semiconductor devices through ~~said~~ the first member and ~~said~~ the another first  
member.

18. (Currently amended) The method of claim 17, further comprising:  
heating each of the plurality of semiconductor devices.

19. (Currently amended) The method of claim 18, wherein ~~said~~ the heating comprises  
cycling a temperature of each of the plurality of semiconductor devices.

20. (Currently amended) The method of claim 18, wherein ~~said~~ the heating comprises  
varying a temperature of each of the plurality of semiconductor devices.